

BENEQ P400A



THERMAL ALD

- Production proven
- Batch size up to 8m²
- Typical dep rate 1-2 μm/24h
- Typical uniformity <2 % over the batch
- Typical materials Al₂O₃, TiO₂, SiO₂
- Typical substrates:
 - Domes
 - High curvature lenses (dia 1..100 mm)
 - Glass wafer or sheet (coating on both sides)
 - Dies on carrier

BENEQ P400 / P800

PROCESS TYPE

- thermal ALD

USAGE

- production

SUBSTRATE TYPE

- wafers
- glass and metal sheets
- 3D-parts
- Max substrate size:
P400A: 370x470 mm
P800: 730x1200 mm

SUBSTRATE LOADING

- manual

MAIN DIMENSIONS

P400A: 2400x930x2420 mm
P800: 3200x1340x2460 mm

INTEGRATION

- stand-alone